

**CTLDM8002A-M621**  
**SURFACE MOUNT**  
**P-CHANNEL**  
**ENHANCEMENT-MODE**  
**SILICON MOSFET**

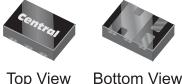


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**DESCRIPTION:**

The CENTRAL SEMICONDUCTOR CTLDM8002A-M621 is a Silicon P-Channel Enhancement-mode MOSFET in a small, thermally efficient, TLM™ 2x1mm package.

**MARKING CODE: CN**



**TLM621 CASE**

**APPLICATIONS:**

- Load/Power Switches
- Power Supply Converter Circuits
- Battery Powered Portable Equipment

**MAXIMUM RATINGS: (TA=25°C)**

Drain-Source Voltage	V <sub>DS</sub>	50	V
Drain-Gate Voltage	V <sub>DG</sub>	50	V
Gate-Source Voltage	V <sub>GS</sub>	20	V
Continuous Drain Current	I <sub>D</sub>	280	mA
Continuous Source Current (Body Diode)	I <sub>S</sub>	280	mA
Maximum Pulsed Drain Current	I <sub>DM</sub>	1.5	A
Maximum Pulsed Source Current	I <sub>SM</sub>	1.5	A
Power Dissipation (Note 1)	P <sub>D</sub>	0.9	W
Operating and Storage Junction Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C
Thermal Resistance (Note 1)	θ <sub>JA</sub>	139	°C/W

**ELECTRICAL CHARACTERISTICS: (TA=25°C unless otherwise noted)**

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I <sub>GSSF</sub> , I <sub>GSSR</sub>	V <sub>GS</sub> =20V, V <sub>DS</sub> =0		100	nA
I <sub>DSS</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0		1.0	μA
I <sub>DSS</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0, T <sub>J</sub> =125°C		500	μA
I <sub>D(ON)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =10V	500		mA
BV <sub>DSS</sub>	V <sub>GS</sub> =0, I <sub>D</sub> =10μA	50		V
V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	2.5	V
V <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =500mA		1.5	V
V <sub>DS(ON)</sub>	V <sub>GS</sub> =5.0V, I <sub>D</sub> =50mA		0.15	V
V <sub>SD</sub>	V <sub>GS</sub> =0, I <sub>S</sub> =115mA		1.3	V
r <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =500mA		2.5	Ω
r <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =500mA, T <sub>J</sub> =125°C		4.0	Ω
r <sub>DS(ON)</sub>	V <sub>GS</sub> =5.0V, I <sub>D</sub> =50mA		3.0	Ω
r <sub>DS(ON)</sub>	V <sub>GS</sub> =5.0V, I <sub>D</sub> =50mA, T <sub>J</sub> =125°C		5.0	Ω
g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =200mA	200		mS

Notes: (1) FR-4 Epoxy PCB with copper mounting pad area of 33mm<sup>2</sup>.

R1 (17-February 2010)

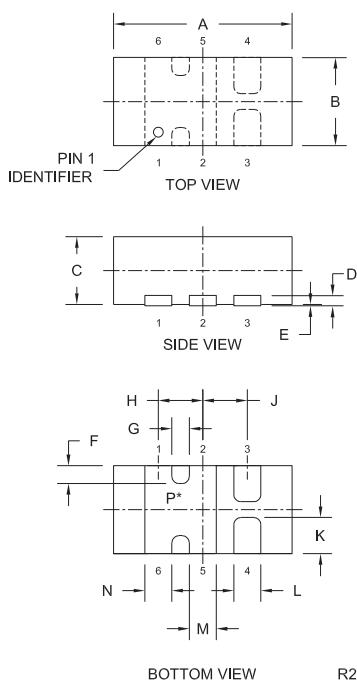
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**ELECTRICAL CHARACTERISTICS - Continued:** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

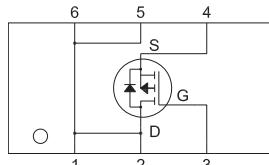
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
$C_{rss}$	$V_{DS}=25\text{V}$ , $V_{GS}=0$ , $f=1.0\text{MHz}$		7.0	pF
$C_{iss}$	$V_{DS}=25\text{V}$ , $V_{GS}=0$ , $f=1.0\text{MHz}$		70	pF
$C_{oss}$	$V_{DS}=25\text{V}$ , $V_{GS}=0$ , $f=1.0\text{MHz}$		15	pF
$t_{on}$ ; $t_{off}$	$V_{DD}=30\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=200\text{mA}$ , $R_G=25\Omega$ , $R_L=150\Omega$	20		ns

**TLM621 CASE - MECHANICAL OUTLINE**



\*Exposed pad P connects pins 1, 2, 5, and 6

**PIN CONFIGURATION**

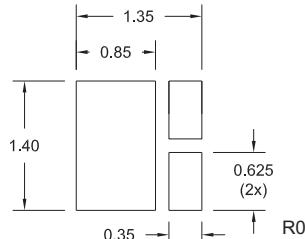


SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.073	0.085	1.850	2.150
B	0.033	0.045	0.850	1.150
C	0.028	0.031	0.700	0.800
D	0.006		0.150	
E	0.000	0.002	0.000	0.050
F	0.008		0.200	
G	0.010		0.250	
H	0.020		0.500	
J	0.020		0.500	
K	0.012	0.020	0.300	0.500
L	0.007	0.012	0.180	0.300
M	0.007	0.012	0.180	0.300
N	0.007	0.012	0.180	0.300

TLM621 (REV: R2)

**SUGGESTED MOUNTING PADS**

(Dimensions in mm)



**LEAD CODE:**

- 1) Drain
- 2) Drain
- 3) Gate
- 4) Source
- 5) Drain
- 6) Drain

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R1 (17-February 2010)